

TSH10

140MHz BANDWIDTH LOW NOISE SINGLE OPERATIONAL AMPLIFIER

■ LOW NOISE: 6nV/√Hz

■ GAIN BANDWIDTH PRODUCT: 140MHz

■ UNITY GAIN STABLE
■ SLEW RATE: 150V/µs
■ STANDARD PIN OUT



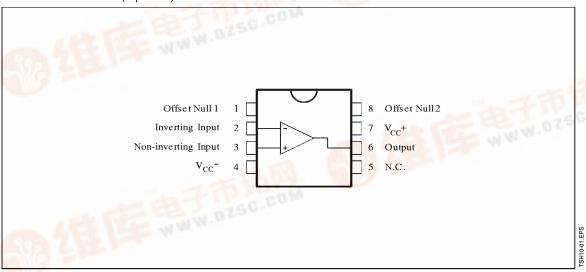
DESCRIPTION

The TSH10 is a low cost wide bandwidth single operational amplifier featuring low input noise of 6nV/\delta Z. Other features as unity gain stability, fast settling time and high linearity make it suitable for any application requiring speed and precision as high resolution video or DAC buffer.

ORDER CODES

Part	Temperature	Pacl	kage	
Number	Range	N	D	1
TSH10I	-40°C, 125°C	Al-Al-	•	

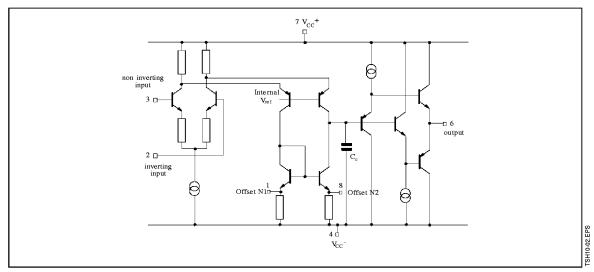
PIN CONNECTIONS (top view)



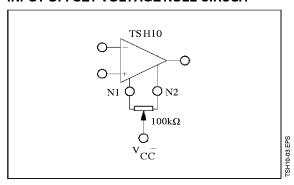
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SCHEMATIC DIAGRAM



INPUT OFFSET VOLTAGE NULL CIRCUIT



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
Vcc	Supply Voltage		±7	V
V _{id}	Differential Input Voltage		±5	V
Vi	Input Voltage Range		±5	V
l _{in}	Current On Inputs Current On Offset Null Pins		±50 ±20	mA
T _{oper}	T	SH10C SH10I SH10M	0 to +70 -40 to +105 -55 to +125	°C
T _{stg}	Storage Temperature Range		-65 to 150	°C

OPERATING CONDITIONS

Symbol	Parameter	Value	Unit
Vcc	Supply Voltage	±3 to ±6	V
V _{ic}	Common Mode Input Voltage Range	V _{CC} ⁻ +2 to V _{CC} ⁺ -1	V

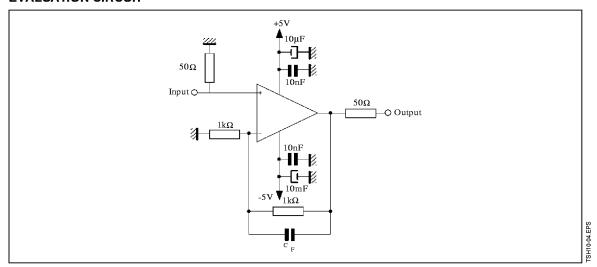
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ELECTRICAL CHARACTERISTICS

 $V_{CC} = \pm 5V$, $T_{amb} = 25^{\circ}C$ (unless otherwise specified)

Symbol	Parameter		Min.	Тур.	Max.	Unit
Vio	Input Offset Voltage			1	10	mV
DV_io	$\begin{array}{c} \text{Input Offset Voltage Drift} \\ T_{\min} \leq T_{\text{amb}} \leq T_{\text{max}} \end{array}$			20		μV/°C
I_{ib}	Input Bias Current			5	30	μA
l _{io}	Input Offset Current			0.1	10	μA
Icc	Supply Current, no load	$V_{CC} = \pm 5V$		20	40	mA
A _{vd}	Large Signal Voltage Gain Vo = ±2.5V	R _L = 100Ω	200	800		V/V
V _{icm}	Input Common Mode Voltage Ran	ige	-3 to +4	-3.5 to +4.5		V
CMR	Common Mode Rejection Ratio	V _{ic} = V _{icm min.}	55	100		dB
SVR	Supply Voltage Rejection Ratio $V_{CC} = \pm 5V$ to $\pm 3V$		45	70		dB
Vo	Output Voltage	$R_L = 100\Omega$	± 2.5	+3.5 -3.7		V
lo	Output Short Circuit Current $V_{id} = \pm 1V$, $V_0 = 0V$			±70		mA
GBP	Gain Bandwidth Product $A_{VCL} = 100$, $R_L = 100\Omega$, $f = 7.5$	5MHz		140		MHz
SR	Slew Rate $V_{in} = \pm 2V$, $A_{VCL} = 1$, $R_L = 100$	Ω		150		V/µs
en	Equivalent Input Voltage Noise	f = 1MHz		6		$\frac{\text{nV}}{\sqrt{\text{Hz}}}$
Øm	Phase Margin $A_{VM} = 1, R_L = 100\Omega, C_L = 15pl$	=		40		Degrees

EVALUATION CIRCUIT



PRINTED CIRCUIT LAYOUT

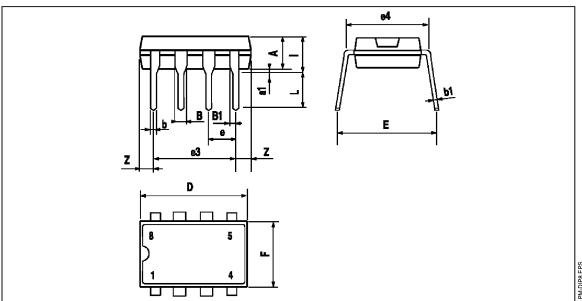
As for any high frequency device, a few rules must be observed when designing the PCB to get the best performances from this high speed op amp.

From the most to the least important points:

- Each power supply lead has to be bypassed to ground with a 10nF ceramic capacitor very close to the device and a 10μF tantalum capacitor.
- To provide low inductance and low resistance common return, use a ground plane or common point return for power and signal.
- All leads must be wide and as short as possible especially for op amp inputs. This is in order to decrease parasitic capacitance and inductance.
- Use small resistor values to decrease time constant with parasitic capacitance. Be aware on TSH10 device of the lio error and input noise currents with high feedback resistor values.
- Choose component sizes as small as possible (SMD).
- On output, decrease capacitor load so as to avoid circuit stability being degraded which may cause oscillation. You can also add a serial resistor in order to minimise its influence.
- One can add in parallel with feedback resistor a few pF ceramic capacitor C_F adjusted to optimize the settling time.

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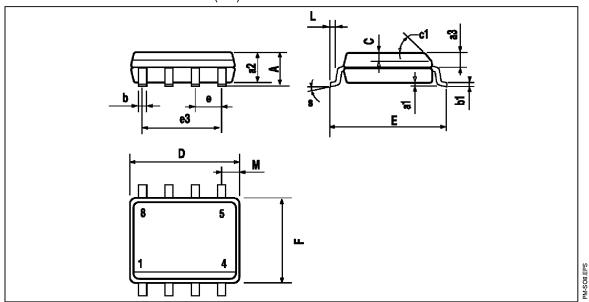
PACKAGE MECHANICAL DATA 8 PINS - PLASTIC DIP



Dimensions		Millimeters		Inches		
Dimensions	Min.	Тур.	Max.	Min.	Тур.	Max.
Α		3.32			0.131	
a1	0.51			0.020		
В	1.15		1.65	0.045		0.065
b	0.356		0.55	0.014		0.022
b1	0.204		0.304	0.008		0.012
D			10.92			0.430
E	7.95		9.75	0.313		0.384
е		2.54			0.100	
e3		7.62			0.300	
e4		7.62			0.300	
F			6.6			0260
i			5.08			0.200
L	3.18		3.81	0.125		0.150
Z			1.52			0.060

PACKAGE MECHANICAL DATA

8 PINS - PLASTIC MICROPACKAGE (SO)



Dimensions	Millimeters			Inches		
Dimensions	Min.	Тур.	Max.	Min.	Тур.	Max.
Α			1.75			0.069
a1	0.1		0.25	0.004		0.010
a2			1.65			0.065
а3	0.65		0.85	0.026		0.033
b	0.35		0.48	0.014		0.019
b1	0.19		0.25	0.007		0.010
С	0.25		0.5	0.010		0.020
c1			45°	(typ.)		
D	4.8		5.0	0.189		0.197
E	5.8		6.2	0.228		0.244
е		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.150		0.157
L	0.4		1.27	0.016		0.050
М			0.6			0.024
S	8° (max.)					

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